



Leader in Superabrasive Finishing Systems

Hyprez Planarization & Polishing Pads



Engis® offers a full selection of pads and cloths to meet demanding polishing and planarization requirements for industrial as well as advanced material finishing. In addition to industry standard pads, Engis can engineer and supply special pads to meet your needs.

Qualification criteria makes our cloths the best available in the industry. Using an array of test materials and slurries, extensive evaluations are performed to ensure these pads meet Engis exacting standards for optimum systems performance.

Most offerings are available with or without pressure sensitive adhesive backing. In addition, perforations or grooving are available

ENGIS is the Industry Leader in Pioneering New Technologies & Applications.

Contact us today to learn more about our 6-Step Superabrasive "Systems Approach"

PAD APPLICATIONS

- Optical components: LiNbO₃, CaF₂, MgF₂, Si, Ge, KTP, DKDP, etc.
- Planarization of MEMS structures
- Semiconductor materials: InP, Sapphire, GaSb, InSb, SoS, SiC, GaN, etc.
- Polishing of high grade metal substrates: Titanium, Nickel, Copper, Gold, etc.
- Industrial metals: Aluminum, Carbide, Steel, Bronze, etc.
- Industrial Ceramics, Glass & Quartz

WE OFFER A FULL LINE OF HYPREZ® PRODUCTS:

- Superabrasive Powders
- Fine Grinding, Lapping & Polishing Machines
- Composite Lap Plates
- Diamond and Non-Diamond Lapping & Polishing Slurries
- Diamond Compound and Lubricants
- Conditioning Rings

ENGIS CORPORATION

Leader in Superabrasive Finishing Systems
105 W. Hintz Road, Wheeling, IL 60090-6038
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LAPPING / POLISHING



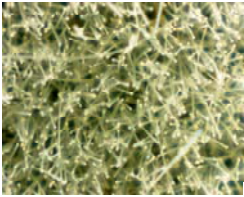


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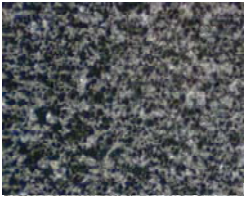
Pad Selection & Application Guide

EJC-10
HLM-3H
HLM-4F
HP-MC-BLK/POLY
HP-S-BRN
HP-S-GRY
HS4/530N2700
HS4/630
HS4/SU
HS4/SU7
HS4/SU4 BLK
HSC-1MP

MEDIUM NAP



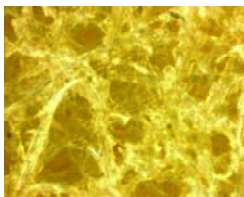
MICRO CELL



WOVEN



RIGID NON-WOVEN



		EJC-10	HLM-3H	HLM-4F	HP-MC-BLK/POLY	HP-S-BRN	HP-S-GRY	HS4/530N2700	HS4/630	HS4/SU	HS4/SU7	HS4/SU4 BLK	HSC-1MP
TYPE	Rigid Non-Woven Pad							X		X	X		X
	Woven Cloth		X	X									
	Micro Cell Pad				X							X	
	Medium Nap	X				X	X		X				
EDGE ROUNDING	High	X					X		X				
	Medium				X	X		X				X	
	Low		X	X						X	X		X
DIAMOND SIZE	Colloids	X			X	X		X	X	X	X	X	X
	0.05 Micron	X			X		X			X	X	X	
	0.1 Micron	X		X	X	X	X			X	X	X	X
	0.25 Micron	X		X	X	X	X	X		X	X	X	X
	0.5 Micron	X		X	X	X	X	X		X	X	X	X
	1 Micron			X	X	X	X	X		X	X	X	X
	3 Micron		X	X	X	X	X	X		X	X	X	X
	6 Micron		X			X				X			X
	9 Micron		X										X
	15 Micron		X										X
	30 Micron		X										
USES	45 Micron		X										
	Rough Polish		X										
	Intermediate Polish		X	X			X	X		X	X		X
	Final Polish	X		X	X	X	X	X	X	X	X	X	X
COMPARISON	Suba 4							X			X		X
	Suba X							X					
	H4										X		X
	Pellon							X					X
	Politex Supreme				X							X	
	Lam Plan 415		X										
	Lam Plan 431	X				X	X		X				
	Lam Plan 432				X							X	
	Lam Plan 437					X	X						
Lam Plan 450			X						X				

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